





**CSEM** – Swiss  
Technology Innovation  
Center

# Technology Transfer to Industry





# APPLIED RESEARCH

Development of deep technology bricks through public funding



Valorization through direct industry mandates following a full cost model (time and material)

## TECH TRANSFER

# CSEM AT A GLANCE

We are a public-private, non-profit Swiss **technology innovation center**

We enable competitiveness by **developing and transferring world-class technologies to the industrial sector**



**1984**  
FOUNDED



**600**  
SPECIALISTS  
in 2023

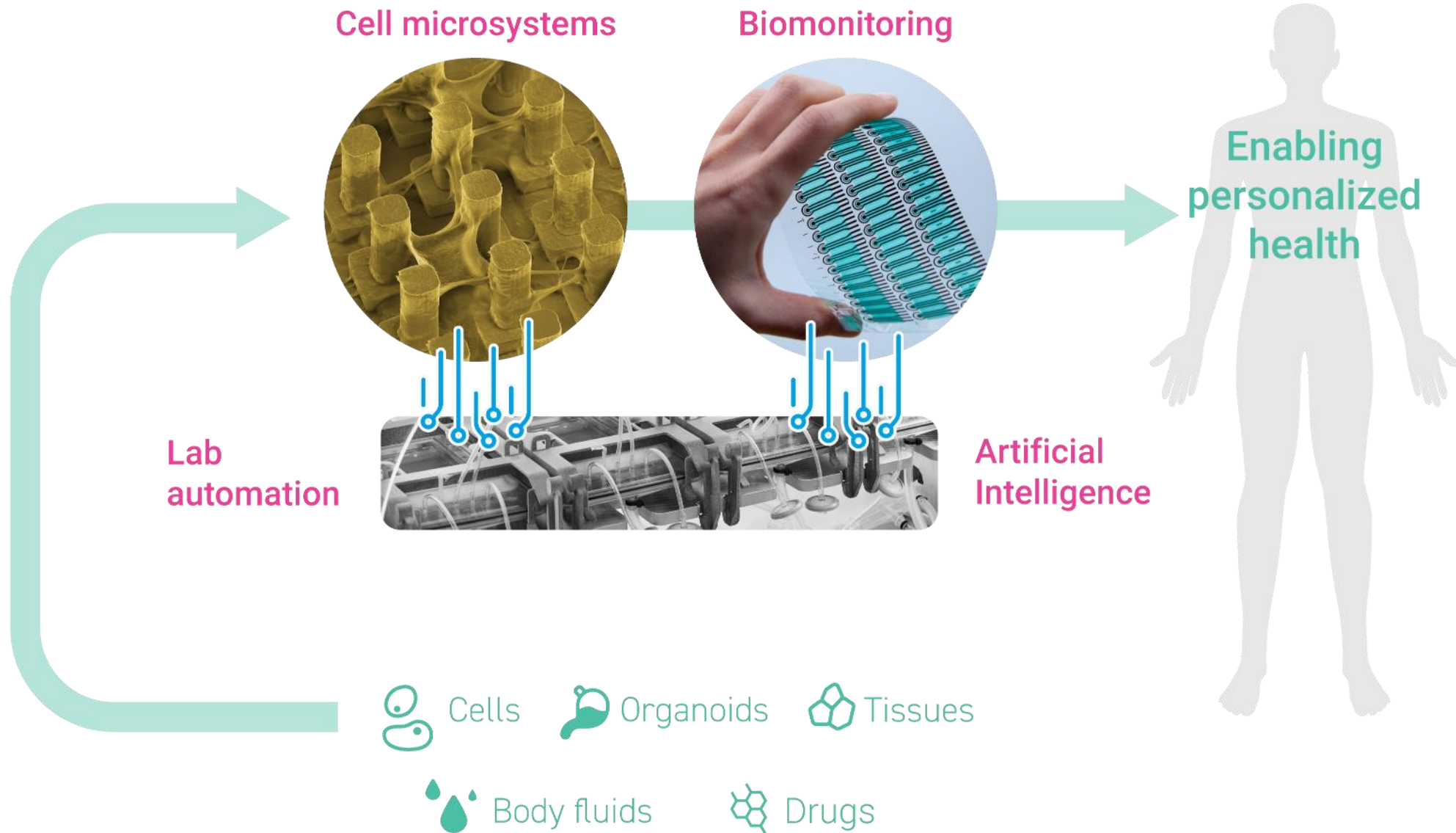


**100.4**  
MIO TURNOVER  
in 2022



**> 50**  
VENTURES  
since 1984

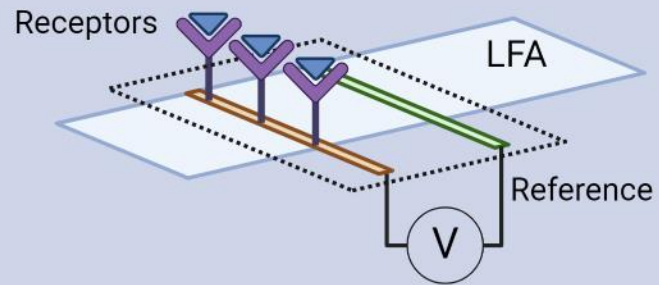
# TOOLS FOR LIFE SCIENCES



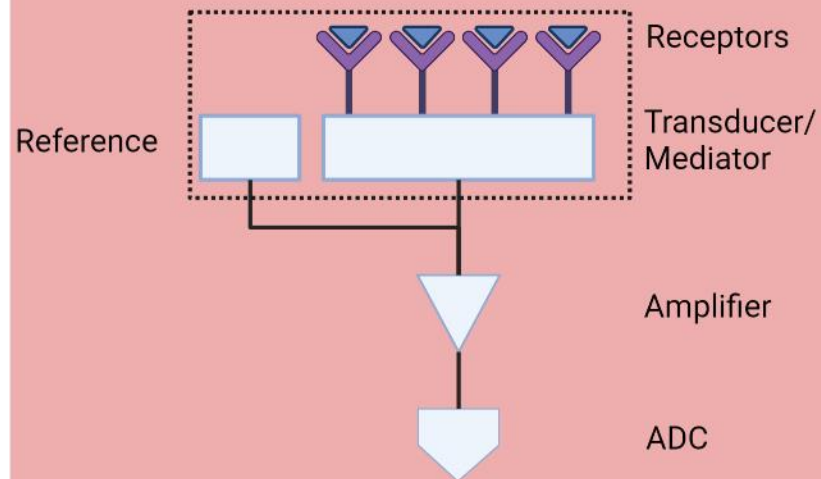


# SENSING???

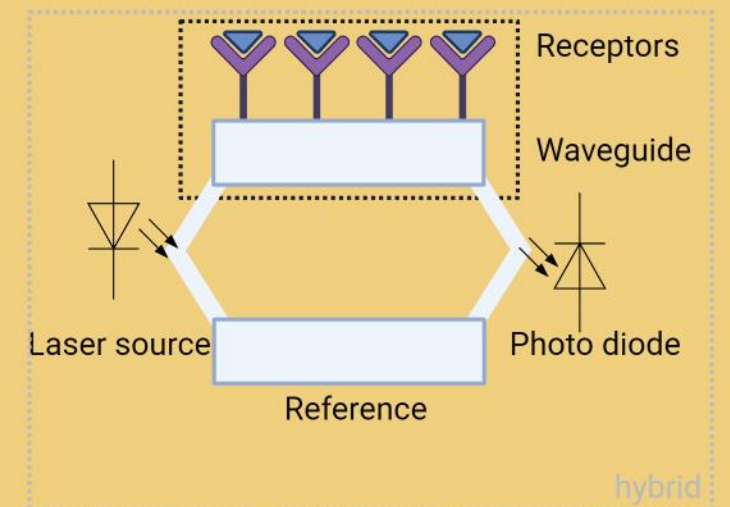
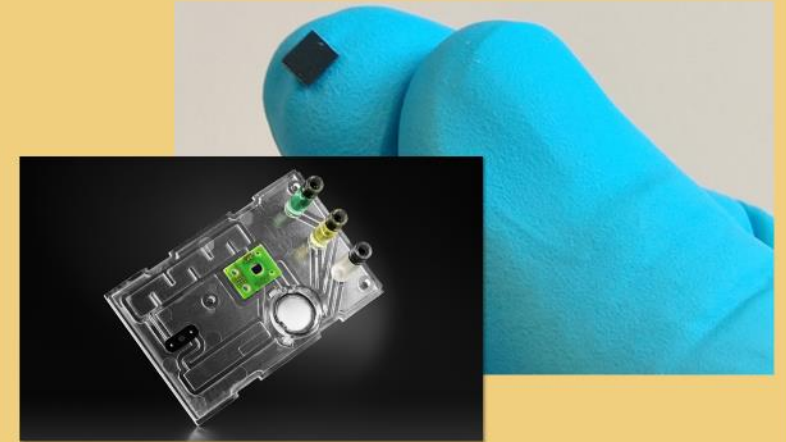
(e) Lateral flow assay (LFA)



Electro chemical sensors

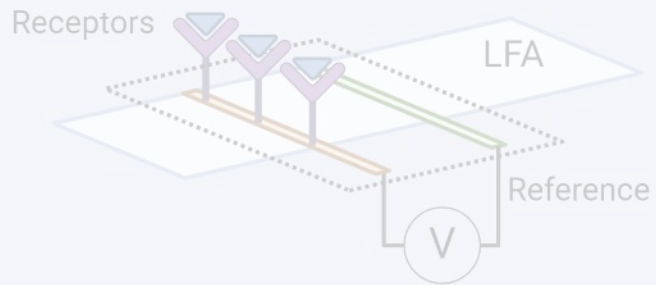


Photonic integrated circuit (PIC)

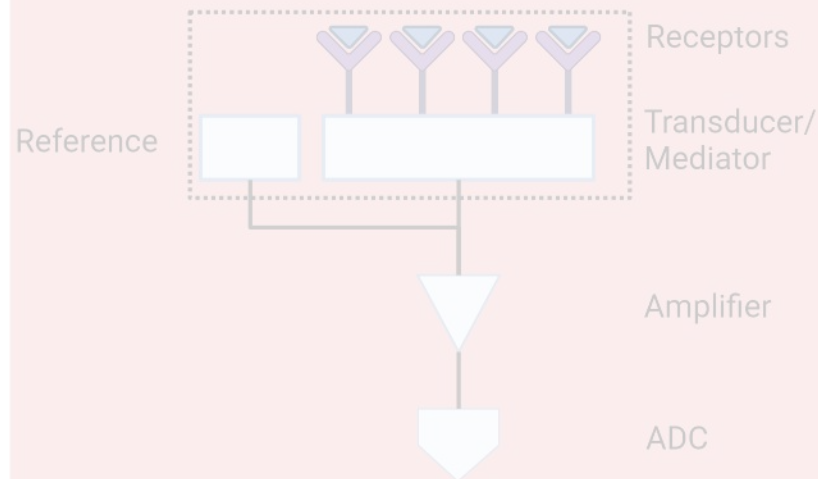


# PIC INTEGRATION

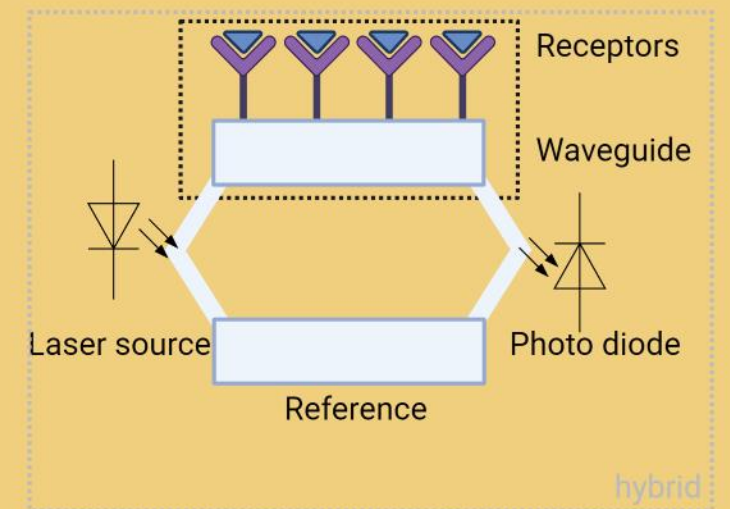
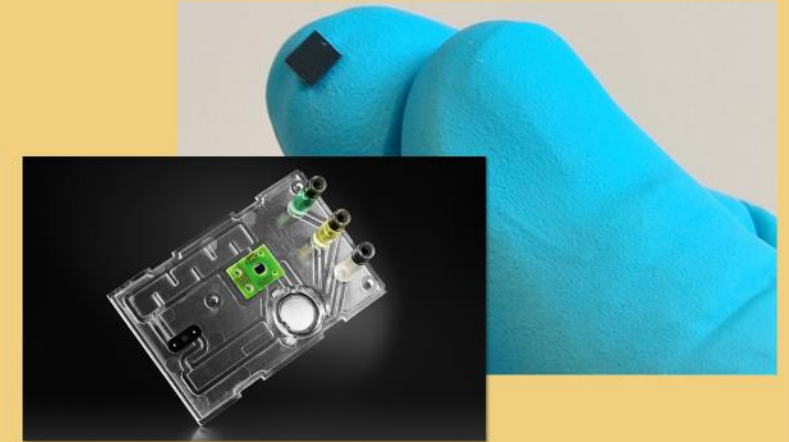
(e) Lateral flow assay (LFA)



Electro chemical sensors

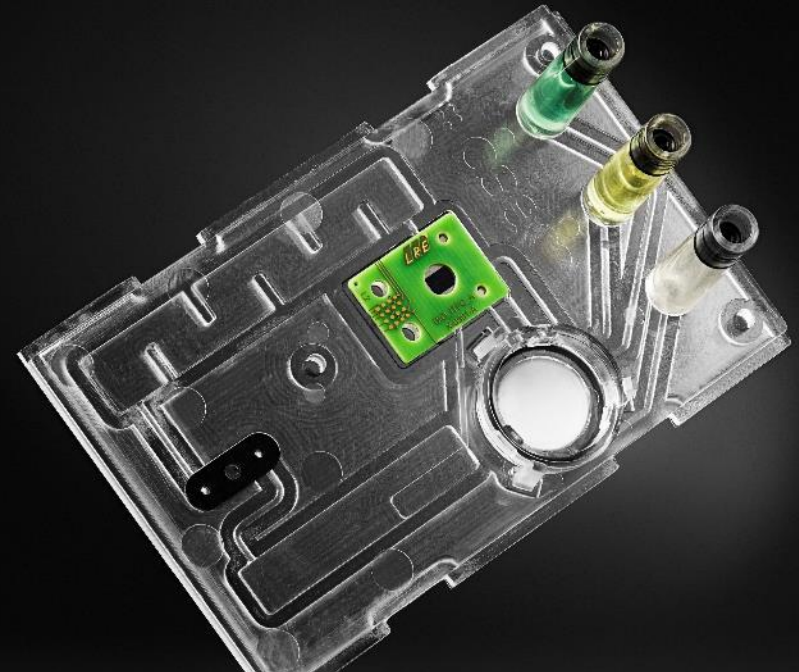
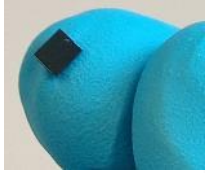


Photonic integrated circuit (PIC)



# COMPLEMENTARY DIAGNOSTICS PHOTONICS PLATFORM

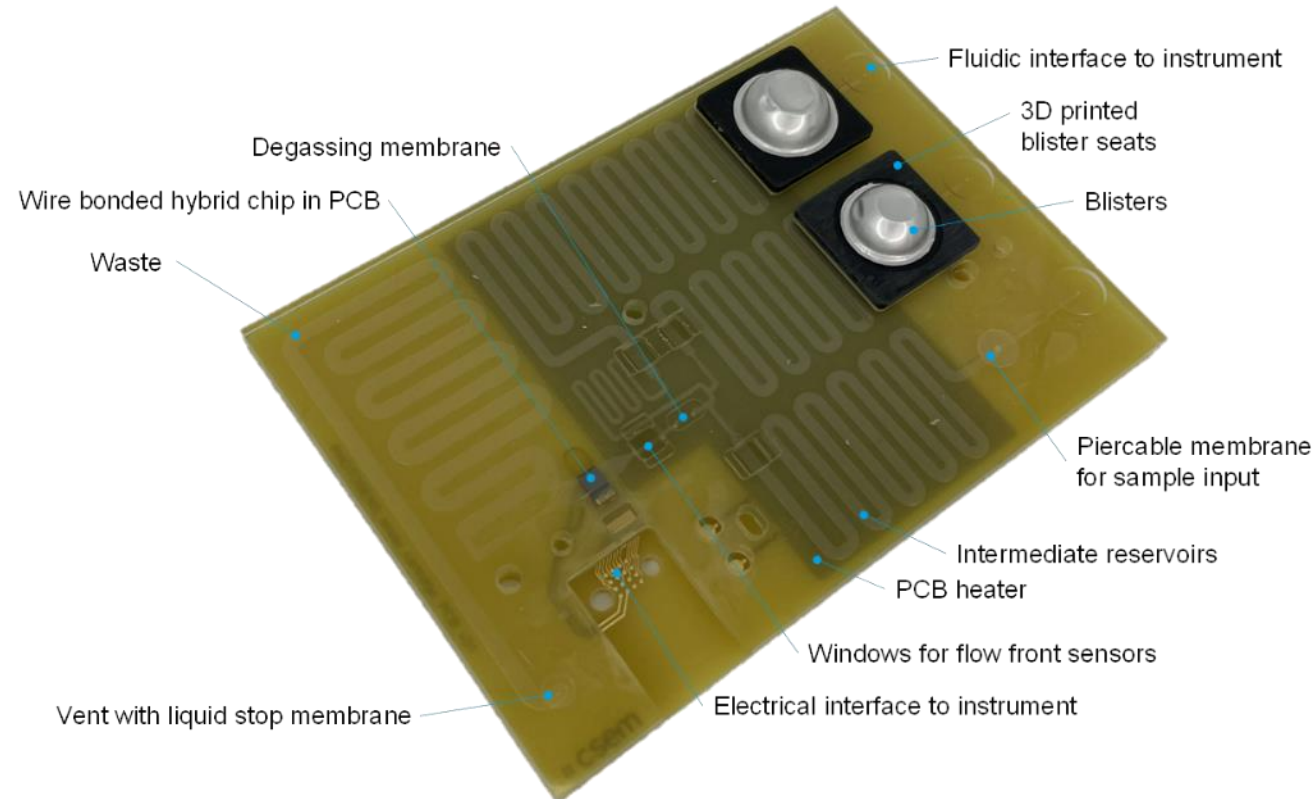
- Protein signature detection
- Use case: Breast and prostate cancer
- Functionalized PIC integrated in microfluidic sample preparation cartridge
- Integrated sample preparation
- Liquid stored on cartridge
- On cartridge valving





# AQUA CULTURE PATHOGEN DETECTION

- Pathogen detection
- Reduction of antibiotics by correct treatment
- Liquid stored on cartridge
- Hybrid PIC with only electrical interface to instrument
- On cartridge heating



# INTERFACES

- **Fluidic interface**

- Exposure to liquids
- Sealing

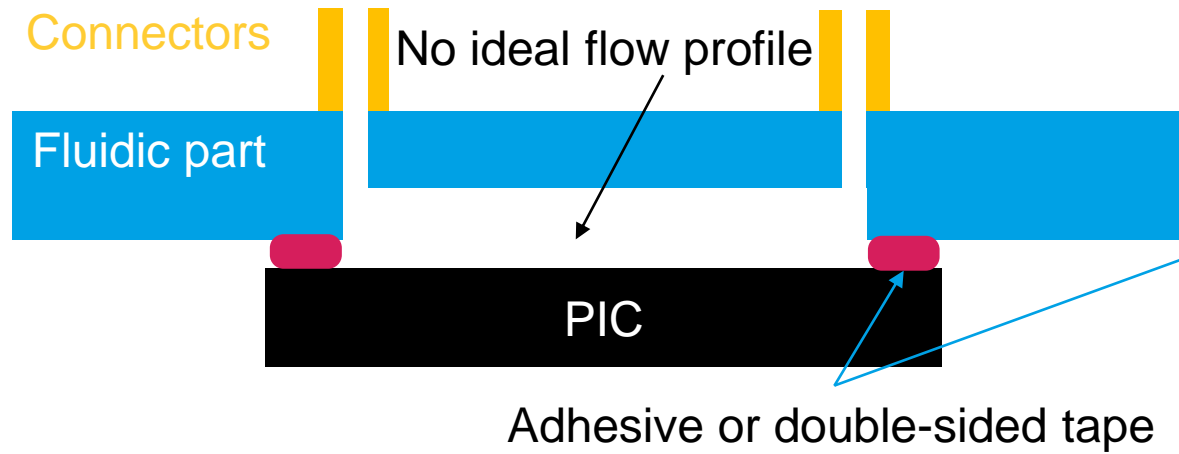
- **Photonic/Electronic interface**

- Dry
- Allow access to wave guides



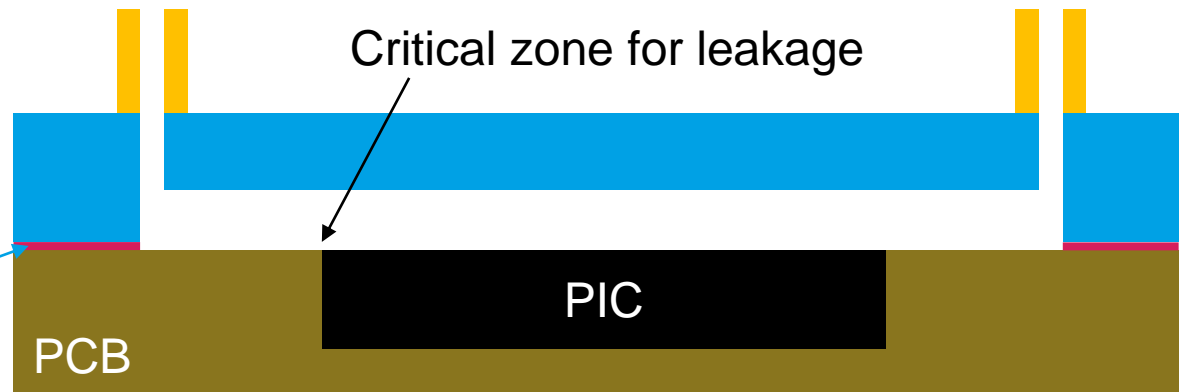
# FLUIDIC INTERFACE: PIC INTEGRATION METHODS

## On-Channel method



- Simple bonding
- Waste of chip area
- Flow profile not ideal

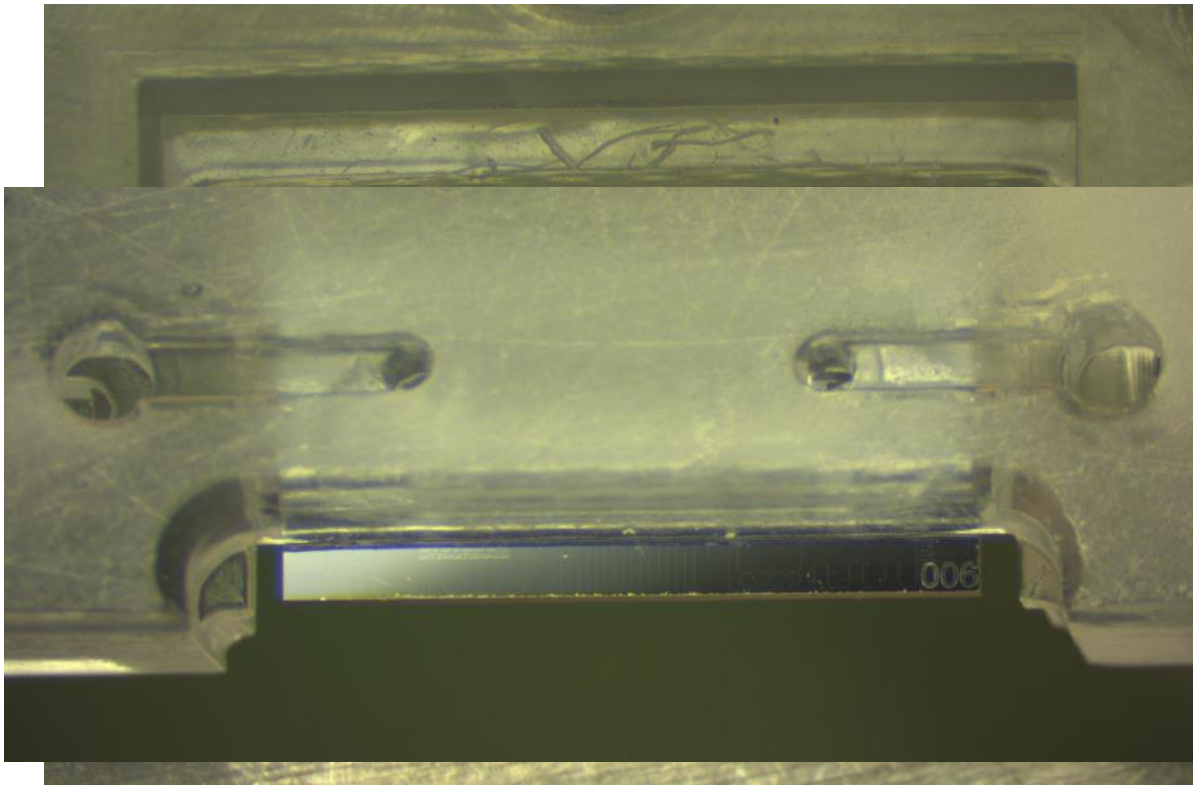
## In-Board method



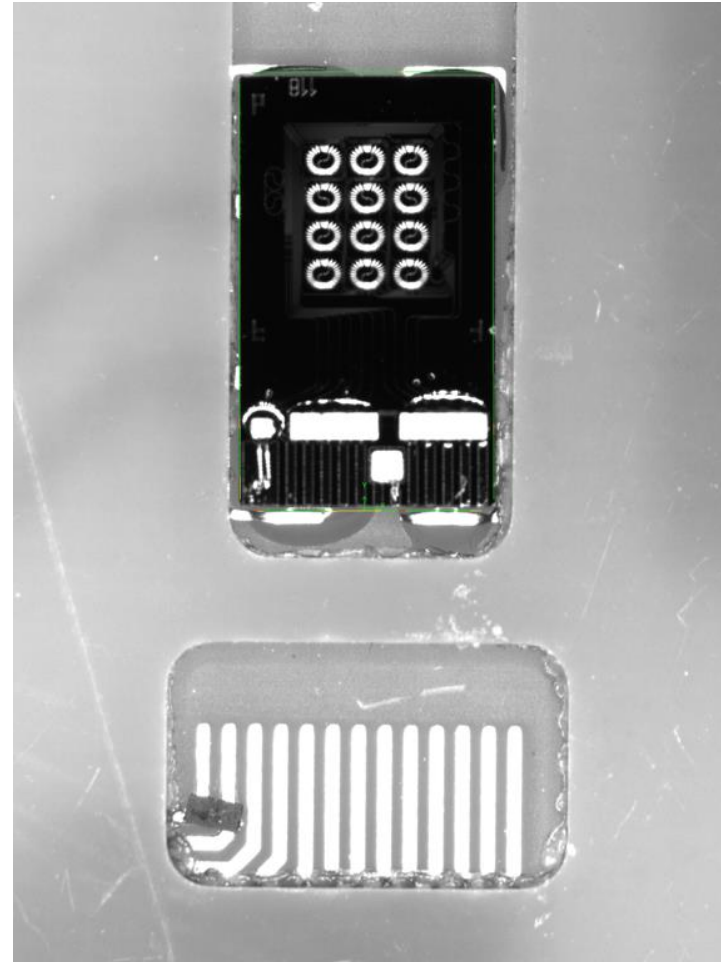
- Challenging bonding
- Smallest chip possible
- Ideal flow profile
- Separate components

# PIC INTEGRATION METHODS

## On-Channel method



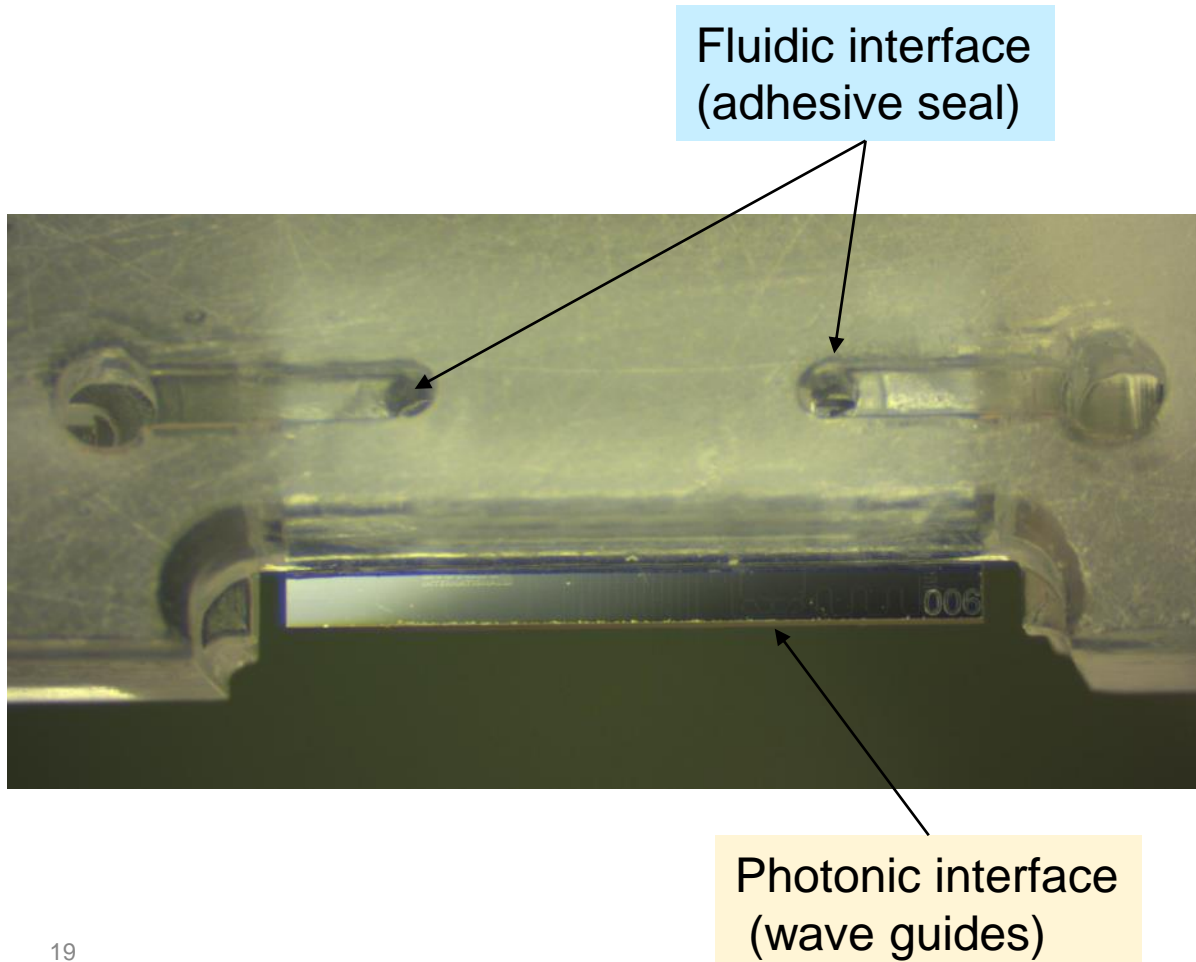
## In-Board method



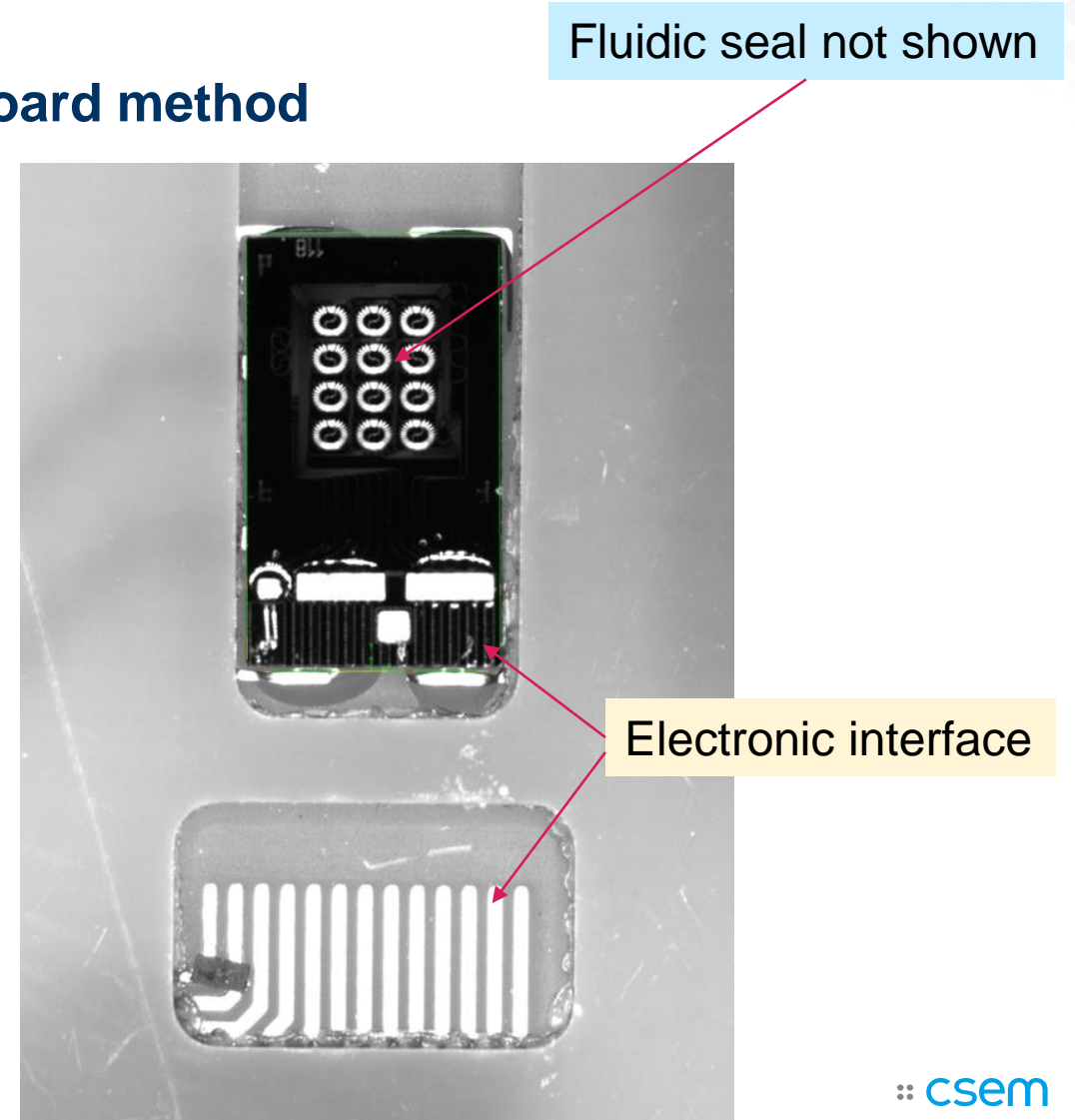


# PIC INTEGRATION METHODS

## On-Channel method



## In-Board method



# ADHESIVE BONDING APPROACHES

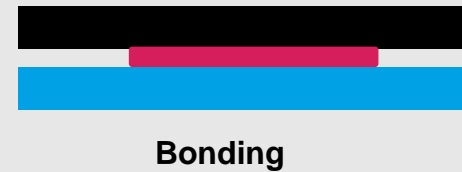
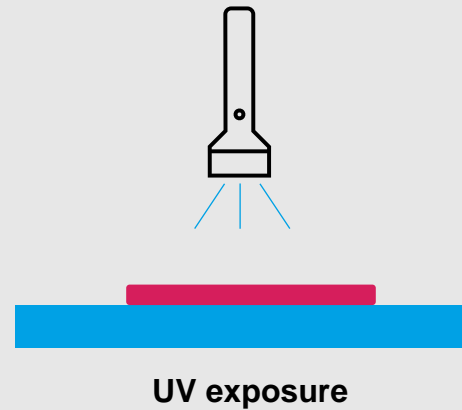
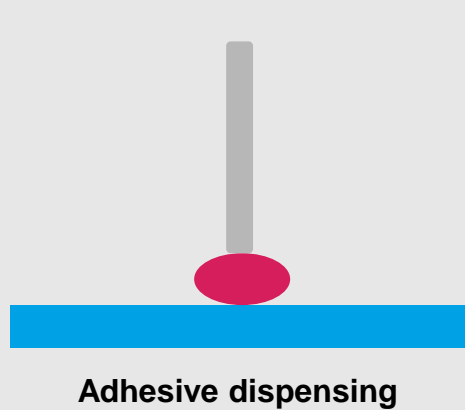
## Bond material

- Epoxy
- Acrylate
- Silicone
- Cyanoacrylate

## Curing mechanisms

- UV exposure
- RTV
- moisture
- UV pre-exposure for opaque components

### UV pre-exposure





# MANUFACTURING



Class 10'000 clean room  
Automated pick and place  
+/- 20um alignment accuracy  
Chip integration  
Tape bonding

## DISPOSABLE

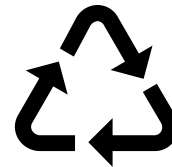
VS

## RE-USABLE

- **Single** sterilisation cycle
- and/or single cleaning cycle
- Short term exposure to test fluid
  - Toxicity
  - Impact on signal through leaching
- Leak tight



- **Multiple** sterilisation cycles
  - Steam!
- Multiple cleaning cycles
- Multiple exposures to test fluid
- Repeated mechanical loading
- Leak-tight or hermetic



# STERILISATION / AUTOCLAVING/CLEANING

- Leak tightness, mechanical function and non-toxicity might be compromised by repeated sterilisation
- Leaks may endanger the operator, damage the instrument and the electronics
- CSEM's view:

Encapsulation	Many Autoclave cycles (>10)	Few autoclave cycles (2-5)	Many EtO	Single EtO	Corrosive environment	Alcohol cleaning	Diluted NaOH
Tape bonding	X	High risk	Low risk	Low risk	✓	Low risk	Unknown
Adhesive bonding	X	High risk	Low risk	✓	✓	✓	Unknown
Metal soldering	Low risk	✓	✓	✓	High risk	✓	✓
Diffusion bonding (Thermocompression, laser assisted diffusion)	Low risk	✓	✓	✓	✓	✓	✓
Glass soldering*	Unknown	Unknown	Unknown	Unknown	Unknown	✓	Unknown

\*Used to create hermetic seals in long-term medical implants (pacemakers etc.)



# CSEM = ONE STOP SHOP





4th edition  
Feb 2025 Basel (CH)

3rd  
**Next  
Gen**

**Organ-  
on-chip &  
Organoids**

24-25 Aug 2023



## PRECISION LIQUID HANDLING WORKSHOP

November 19 - 2024



Networking  
Event Series  
powered by  
Innosuisse

22 OCTOBER 2024 SWISS SYMPOSIUM IN  
POINT-OF-CARE DIAGNOSTICS

NEXT YEAR EVENT - SAVE THE DATE

22nd October, 2024 | Zürich Technopark



## Discover our Life Science Brochure



:: csem



TOOLS for LIFE SCIENCES





FACING THE CHALLENGES OF OUR TIME